WHAT IS CLAIMED IS:

1. A packaging structure comprising:

an electronic component;

a thermal conduction structure;

a first metal layer attached on the electronic component;

a second metal layer attached on the thermal conduction structure, wherein the second metal layer is not electrically connected with the electronic component;

an insulation structure comprising a groove and plural first openings, wherein the electronic component, the thermal conduction structure, the first metal layer and the second metal layer are embedded within the insulation structure, wherein the groove is located in an edge of the insulation structure; and

a first metal re-distribution layer contacted with the thermal conduction structure and one side of the second metal layer through the groove and contacted with the first metal layer and the other side of the second metal layer through the plural first openings.

2. The packaging structure according to claim 1, wherein a side of the insulation structure, a second recess of the insulation structure and one side of the second metal layer are defined as a concave.

3. The packaging structure according to claim 1, wherein the packaging structure comprises a first mask, the first metal re-distribution layer comprises plural second openings, and the first mask is disposed on the second opening.

4. The packaging structure according to claim 1, wherein an edge of the thermal conduction structure comprises a first recess and the other edge of the thermal conduction structure comprises a second recess.

5. The packaging structure according to claim 1, wherein the electronic component comprises a first conducting terminal and a second conducting terminal, the insulation structure comprises plural third openings corresponding

to the thermal conduction structure, the first conducting terminal and the second conducting terminal.

6. The packaging structure according to claim 5, wherein the packaging structure further comprises:

a second metal re-distribution layer disposed on the insulation structure and connected with the thermal conduction structure, the first conducting terminal and the second conducting terminal through the corresponding third openings, wherein the second metal re-distribution layer comprises plural fourth openings;

a second mask disposed on the second metal re-distribution layer and connected with the insulation structure through the plural fourth openings, wherein the second mask comprises plural fifth openings;

a third metal re-distribution layer disposed on the second mask and connected with the second metal re-distribution layer through the plural fifth openings, wherein the third metal re-distribution layer comprises plural sixth openings; and

a third mask disposed on the third metal re-distribution layer and connected with the second mask through the plural sixth openings.